

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: KOYAMA, et al
Serial No.: Not yet assigned.
Filed: Herewith (December 18, 2001)
For: CMP ABRASIVE, METHOD FOR POLISHING SUBSTRATE AND
METHOD FOR MANUFACTURING SEMICONDUCTOR DEVICE USING
THE SAME, AND ADDITIVE FOR CMP ABRASIVE
Group: Not yet assigned.
Examiner: Not yet assigned.

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

December 18, 2001

Sir:

Prior to examination on the merits, please amend the above-identified application as follows:

IN THE CLAIMS:

Please amend Claims 3 - 7 and 10 - 11 as follows:

3. (amended) The CMP abrasive according to Claim 1, wherein said organic polymer is a compound containing either one or both of a nitrogen atom and an oxygen atom in a molecular structure.

4. (amended) The CMP abrasive according to Claim 1, wherein said organic polymer is a compound having an adsorption ratio of 50% or more with respect to silicon oxide particles